

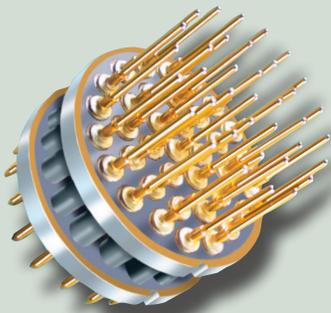


Introduction to Filter Connectors Multilayer Ceramic Planar Capacitor Arrays

Multilayer Ceramic Planar Capacitor Arrays

Planar, multi-layer ceramic capacitive filters offer reduced size and improved performance compared to discrete discoidal or tubular capacitors. Planar array filter devices have the advantage, especially when compared to capacitive filters integrated at the circuit board level, of being bidirectionally effective at attenuating unwanted noise travelling into and out of equipment enclosures.

As mentioned above, the planar array can be designed with different capacitive values on individual pins, and pin groupings, and can also be selectively equipped with surge protection diodes. The ability to accommodate such Transient VoltageSuppressions (TVS) diodes to protect against voltage spikes from transient sources such as EMP, lightning or Electrostatic Discharge (ESD) is an additional strength of the planar array design. The planar array package can also easily accommodate ferrite elements to add inductance to the filter device. For these reasons and more, the planar array is the most common filter type specified in military aerospace and other high-performance applications.



Multipin planar array filter device, assembled with its ferrite elements and connector contacts, ready for insertion into the connector shell. The flexible design allows for different capacitive values on individual pins as well as the integration of hybrid contacts such as optical termini.

The metal electrodes are plated on alternate ceramic layers with a 'hot' or ground electrode to match the contact pattern of the chosen connector. This results in a discrete capacitance value per hole—ultimately determining the EMI attenuation properties of the assembled filter device. After the layer-cake of dielectric materials and conductive elements is assembled, it is fired at high temperature to create a unified, monolithic structure.

As the figure below illustrates, the planar array is fabricated such that the capacitor positions align exactly to the pin layout positions of the connector. When combined with inductive ferrite elements, TVS diodes or other special circuitry, the final assembly is ready for insertion into the connector shell. The incorporation of filter elements into a standard cylindrical or rectangular connector will necessarily increase the overall length of the package. The extra real estate is usually added to the inside-the-box (non-mating) side of the connector receptacle. Another approach is to attach a connector adapter, or go-between, outfitted with the filter device, to the connector plug. This approach has the advantage of not requiring any dimensional changes in box design or receptacle connector package.

Typically, custom-configured planar arrays, with unique capacitive elements and values, are required to effectively address complex EMI problems such as might be encountered in an avionics bay or in the body of a missile. For this reason, planar array fabrication is accomplished using the most advanced CAD software and CNC machine tools. As critical EMI problems are often discovered late in the development process—perhaps only after equipment has been installed for use—it is critical that turnaround times in design and fabrication of custom designs are kept to a minimum. Glenair is committed to meeting the most aggressive delivery requirements for planar array type filter connectors.

Dimensions in inches (millimeters) and are subject to change without notice.

© 2013 Glenair, Inc.

U.S. CAGE Code 06324

Printed in U.S.A.